## CNN for Wafer Back and Edge ADC

EG3611A Industrial Attachment Final Presentation

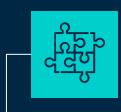
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### TABLE OF CONTENTS



01

RECAP OF PART 1

Using CNN for Wafer Edges only



02

NEW PROJECT REQUIREMENTS

Wafer Backside and System Architecture



03

BACKSIDE ADC

More Classes but Same Concept

### TABLE OF CONTENTS



04

SYSTEM DESIGN

Data Flow, System Flow and Coding it all out



05

CHALLENGES & LEARNINGS

Planning, Scaling, Integrating



06

REFLECTION & CONCLUSION

Of this 4-month Machine Learning Internship

### RECAP OF PART 1

Using CNN for Wafer Edges only

### Wafer Edge ADC

- Defects can occur on the backside or edges (both my focus), and frontside
- "Defects" flagged by the machines are often false positives
- To gather wafer edge images and train a machine learning (ML) model
- Goal: predict if there is chipping, or "aok" (all-OK)





### NEW PROJECT REQUIREMENTS

Wafer Backside and System Architecture

### New Problems Breakdown

- Backside ADC
- ADC System Design and Architecture
  - Data Flow and Folder Structure
  - Parsing KLA Files
  - o Bundling into a System
  - Building a Graphical User Interface (GUI)



### BACKSIDE ADC

More Classes but Same Concept

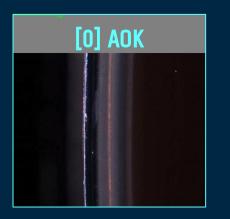


### Wafer Backside ADC

- 5 classes instead of 2
- Same problems still exist: unbalanced and limited data
- New problems: some classes look similar or vague
- Solved similarly with pre-trained CNN models

	test_correct	test_total	test_acc
2Dec2021-1339	3027	3124	96.90%
8Dec2021-1501	3024	3124	96.80%
22Dec2021-1753	3035	3124	97.15%

### Wafer Backside 5 Classes











### SYSTEM DESIGN

Data Flow, System Flow and Coding it all out

### Data Flow: Current State

Wafer Inspection

Wafer Lots to be Shipped Out

**Load Wafers** 



### **AVI Machine**

"Full Inspection"

- 1. Frontside
- 2. Backside
- 3. Edges



Klarity Defect



**Interprets Outputs** 

"K Drive"

AVI Outputs

- 1. KLA File
- 2. FBE Images

### Data Flow: Future State with ADCS

**Wafer Inspection** 

Wafer Lots to be Shipped Out



- Models Loading
- User Interface

### Scan Interpretation

**Klarity Defect** 



Extract Relevant Images





Predict



### **AVI Machine**

"Full Inspection"

- 1. Frontside
- 2. Backside
- 3. Edges

### **ADC** Drive

**AVI Outputs** 

- 1. KLA File
- 2. FBE Images

### "K Drive"

**AVI** Outputs

- 1. **Modified** 
  - KLA File
- 2. FBE Images



### ADC System Flow

- 1. KLA files and images from AVI are fed into ADC drive
- 2. ADCS continuously polls ADC drive for KLA files
- 3. If KLA files found, start **Model Inference**; else, poll again after some time
  - a. Reads oldest KLA file and stores relevant information
  - b. Checks if filenames referenced in KLA file can be found
  - c. Feed FS/BS/EN images into their respective models
  - d. FBE models classify images and modify CLASSNUMBERs in KLA file
  - e. Results also saved to CSV files for future reference
  - f. Move and copy KLA file and images to correct drives
- 4. Repeat

### CHALLENGES AND LEARNINGS

Planning, Scaling, Integrating



Challenges	Learnings	
Planning and architecting the system	Note down all potential logic holes	
Coding for readability and extensibility	OOP and DRY programming concepts	
Usability and user interfaces	Start from simple CLI then to GUI	
This entire journey	Being independent and trusting myself	

### REFLECTION & CONCLUSION

Of this 4-month Machine Learning Internship



# MAIN TAKEAWAY DON'T BE AFRAID OF WHAT I DON'T KNOW

